

A6
--As can be seen in Figure 1, leads 62 serve as the common source connections while leads 56 serve as the drain connections for the first or top die. Lead 12a serves as the gate connection for the first die while lead 12b serves as the gate connection for the second die. Parallel connection of the top and bottom dies may be specially routed on the circuit board for optimum electrical performance. Isolating the connections of the top and bottom dies may be an option depending upon the device application.--

IN THE CLAIMS:

Please cancel claims 5 and 6.

IN THE DRAWINGS:

Applicant submits herewith proposed Figures 1-4, with the proposed changes indicated in red, for the Examiner's approval. It is respectfully submitted that no new matter has been added.

IN THE TITLE:

Please change the title so that it reads in its entirety:

--SEMICONDUCTOR DEVICE WITH TWO DIES--.

REMARKS

Claims 1-4 are pending.

The Examiner has objected to the drawings for several reasons.

Accordingly, applicant submits herewith proposed amended drawings for the Examiner's approval. Applicant has enlarged the original drawings and removed extraneous words. This should help illustrate the structure of applicant's invention without the perception of new matter possibly being added. For example , it is now clearer that the dies are located on opposite sides of the leadframe and that the lead rail 53 is separate from the leadframe, as are the gate attach areas 24, 25. The few proposed changes are indicated in red and it is respectfully submitted that no new matter has been added. Applicant has also amended